

ABSTRACT

IPS B27

Printed wiring boards are often joined on a motherboard in order to optimize use of cabinet space. The process of the present invention enables more efficient manufacture and assembly of adjoining printed wiring boards. The steps of the inventive process comprise forming multiple circuits upon a common substrate before the common substrate is separated into separate boards; making interconnections between the separate boards, preferably in situ and before the boards are separated; and separating the common substrate into a plurality of separate interconnected boards. Using the inventive process, interconnections between boards can be fully tested on a single substrate and inventory and handling processes relating to joining of separate boards can be simplified or eliminated.

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